

# 1A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

#### **MECHANICAL DATA**

• Case: SOD-123HE

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

• Polarity: Indicated by cathode band

• Weight: 0.013g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	1	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	45	Α	
T <sub>J MAX</sub>	175	°C	
Package	SOD-123HE		
Configuration	Single die		









SOD-123HE



PARAMETER		SYMBOL	PU1BLSH	PU1DLSH	UNIT
Marking code on the device			U1BLS	U1DLS	
Repetitive peak reverse voltage		$V_{RRM}$	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	1		Α
Surge peak forward current single half	t = 8.3ms		l .	.5	
sine-wave superimposed on rated load	t = 1.0ms	- I <sub>FSM</sub>	100		A
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C

1

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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	R <sub>OJL</sub>	13	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	71	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	19	°C/W

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 0.5A, T <sub>J</sub> = 25°C		0.79	-	V
	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C	W	0.84	0.93	V
	I <sub>F</sub> = 0.5A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.64	-	V
	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.70	-	V
D (2)	T <sub>J</sub> = 25°C		-	2	μΑ
Reverse current @ rated $V_R^{(2)}$	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	10	μΑ
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	19	-	pF
Doverse receivery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	+	-	25	ns
Reverse recovery time	$I_F = 1.0A$ , $di/dt = 50A/\mu s$ , $V_R = 30V$	t <sub>rr</sub>	34	-	
Reverse recovery current		I <sub>RM</sub>	3.4	-	Α
Reverse recovery charge	$I_F = 1.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$	Q <sub>rr</sub>	27	-	nC
Reverse recovery time		t <sub>rr</sub>	19	-	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
PU1xLSH	SOD-123HE	10,000/ Tape & Reel	

## Notes:

1. "x" defines voltage from 100V(PU1BLSH) to 200V(PU1DLSH)

100



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

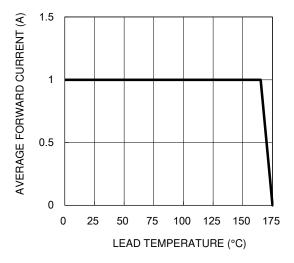


Fig.3 Typical Reverse Characteristics

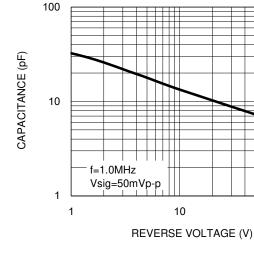
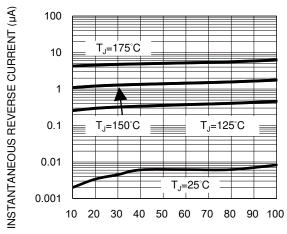


Fig.4 Typical Forward Characteristics

Fig.2 Typical Junction Capacitance



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

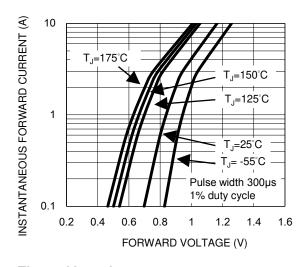
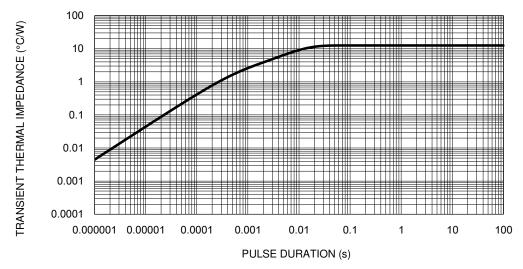


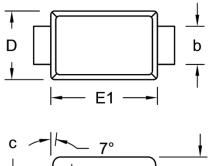
Fig.5 Typical Transient Thermal Impedance

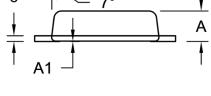


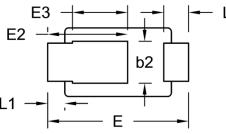


## **PACKAGE OUTLINE DIMENSIONS**



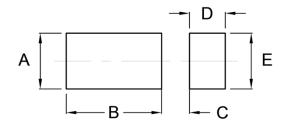






DIM.	Unit (mm)		Unit (	(inch)
DIW.	Min.	Max.	Min.	Max.
Α	0.75	0.85	0.030	0.033
A1	0.00	0.02	0.000	0.001
b	0.85	1.15	0.033	0.045
b2	0.95	1.25	0.037	0.049
С	0.10	0.20	0.004	0.008
D	1.65	1.95	0.065	0.077
E	3.50	3.90	0.138	0.154
E1	2.60	3.00	0.102	0.118
E2	1.90	2.30	0.075	0.091
E3	1.35	1.55	0.053	0.061
L	0.55	0.75	0.022	0.030
L1	0.35	0.55	0.014	0.022

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	2.40	0.094
С	0.70	0.028
D	0.90	0.035
E	1.40	0.055

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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